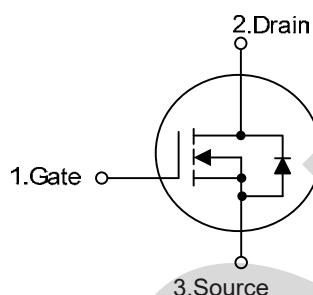
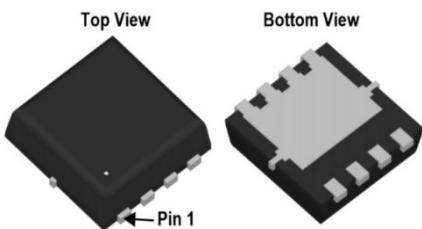


N-Channel Enhancement Mode Power MOSFET

MTR025N10D33

PDFN3*3-8L



| | | |
|------------------------------|-----|----|
| V_{DS} | 100 | V |
| $R_{DS(on)}$ @ $V_{GS}=10$ V | 19 | mΩ |
| I_D | 25 | A |

Features

- 1、Low on – resistance
- 2、Package PDFN3*3-8L
- 3、TRENCH Power MOSFET

Applications

- 1、Portable Equipment and Battery Powered systems
- 2、Power Management in Notebook Computer

Maximum ratings, at TA =25°C, unless otherwise specified

| Symbol | Parameter | Rating | Unit | |
|------------|---|-------------------|-------|---|
| $V(BR)DSS$ | Drain-Source breakdown voltage | 100 | V | |
| V_{GS} | Gate-Source voltage | ±20 | V | |
| I_D | Continuous drain current @ $V_{GS}=10V$ | $T_C=25^\circ C$ | 25 | A |
| | | $T_C=100^\circ C$ | 18 | A |
| I_{DM} | Pulse drain current tested① | $T_C=25^\circ C$ | 100 | A |
| EAS | Avalanche energy, single pulsed | | 16 mJ | |
| P_D | Maximum power dissipation | $T_C=25^\circ C$ | 45 W | |
| TSTG,TJ | Storage and Junction Temperature Range | -55 to 150 | °C | |

Thermal Characteristics

| Symbol | Parameter | Typical | Unit |
|------------------|---|---------|------|
| R _{θJC} | Thermal Resistance, Junction-to-Case | 2.5 | °C/W |
| R _{θJA} | Thermal Resistance, Junction-to-Ambient | 36 | °C/W |

Electrical Characteristics

| Symbol | Parameter | Condition | Min. | Typ. | Max. | Unit |
|--------|-----------|-----------|------|------|------|------|
|--------|-----------|-----------|------|------|------|------|

Static Electrical Characteristics @T_j=25°C (unless otherwise stated)

| | | | | | | |
|---------------------|----------------------------------|--|-----|-----|------|----|
| V(BR)DSS | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 100 | -- | -- | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} =80V, V _{GS} =0V | -- | -- | 1 | μA |
| I _{GSS} | Gate-Body Leakage Current | V _{GS} =±20V, V _{DS} =0V | -- | -- | ±100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 1.2 | 1.8 | 2.5 | V |
| R _{D(on)} | Drain-Source On-State Resistance | V _{GS} =10V, I _D =1A | -- | 19 | 23 | mΩ |
| | | V _{GS} =4.5V, I _D =1A | -- | 26 | 33 | mΩ |
| g _f s | Forward Transconductance | V _{DS} =10V, I _D = 20A | -- | 22 | -- | S |

Dynamic Electrical Characteristics@T_j = 25°C (unless otherwise stated)

| | | | | | | |
|------------------|------------------------------|--|----|------|----|----|
| C _{iss} | Input Capacitance | V _{DS} =50V, V _{GS} =0V , f=1MHz | -- | 822 | -- | pF |
| C _{oss} | Output Capacitance | | -- | 310 | -- | pF |
| C _{rss} | Reverse Transfer Capacitance | | -- | 23,5 | -- | pF |
| R _g | Gate Resistance | V _{DS} =0V, V _{GS} =0V , f=1MHz | -- | 1.62 | -- | Ω |
| Q _g | Total Gate Charge | V _{DS} =50V, I _D =20A , V _{GS} =10V | -- | 22.7 | -- | nC |
| | Gate-Source Charge | | -- | 6.2 | -- | nC |
| | Gate-Drain Charge | | -- | 5.7 | -- | nC |

Switching Characteristics

| | | | | | | |
|---------|---------------------|--|----|-----|----|----|
| Td(on) | Turn-on Delay Time | $V_{DS}=50V$, $V_{GS}=10V$, $I_D=20A$ $R_G=3.0\Omega$, | -- | 15 | -- | ns |
| Tr | Turn-on Rise Time | | -- | 3.2 | -- | ns |
| Td(off) | Turn-Off Delay Time | | -- | 30 | -- | ns |
| Tf | Turn-Off Fall Time | | -- | 7.6 | -- | ns |

Source -Drain Diode Characteristics @Tj = 25°C (unless otherwise stated)

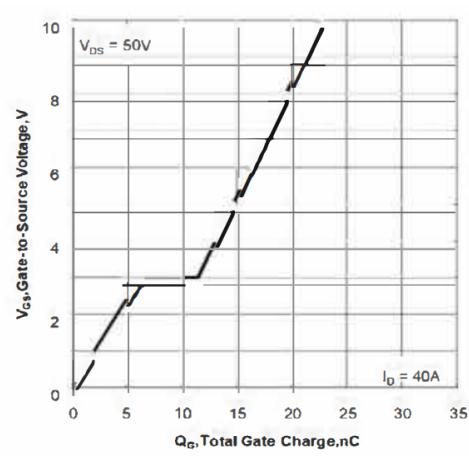
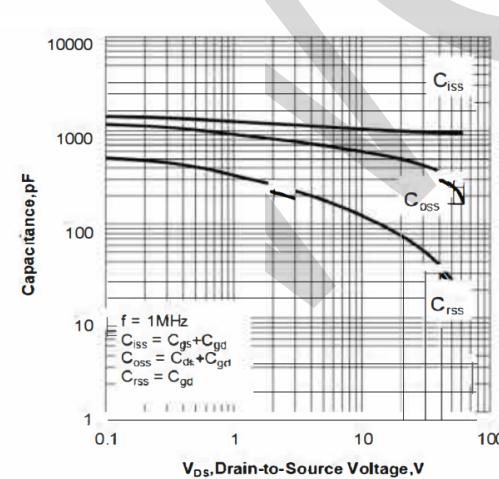
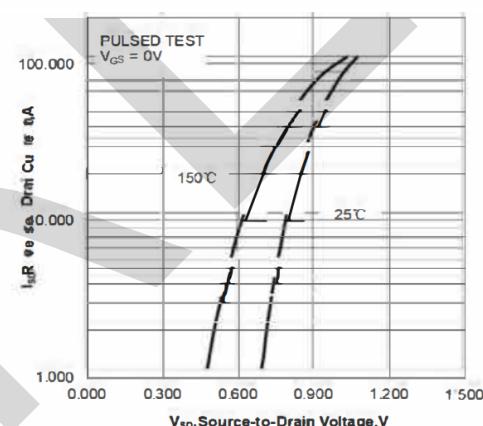
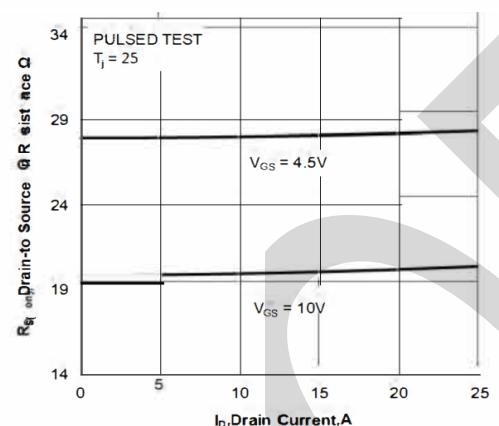
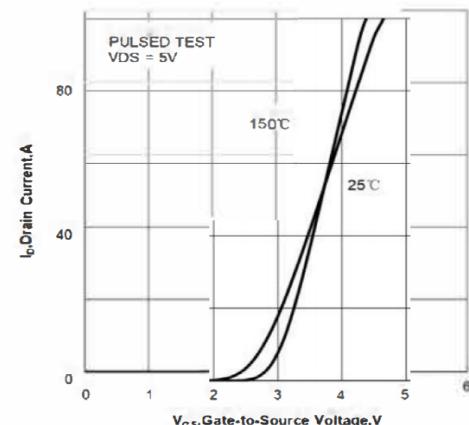
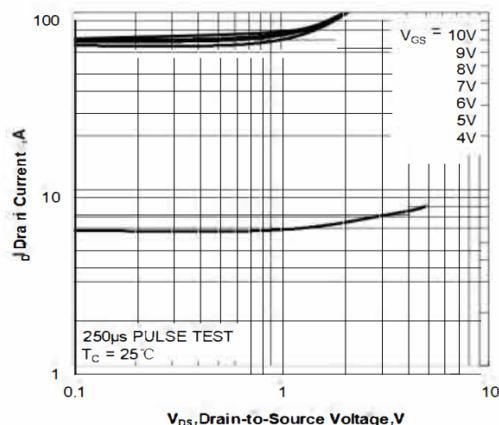
| | | | | | | |
|----------|---------------------------|-----------------------|----|----|-----|----|
| Vsd | Forward on voltage | $I_S=10A, V_{GS}=10V$ | -- | -- | 1.2 | V |
| Is | Diode Forward Current | $T_C = 25^\circ C$ | -- | -- | 25 | A |
| T_{rr} | Reverse Recovery Time ② | $I_F=20A, V_{GS}=0V$ | -- | 45 | -- | ns |
| Q_{rr} | Reverse Recovery Charge ② | $di/dt=100A/\mu s$ | -- | 59 | -- | nC |

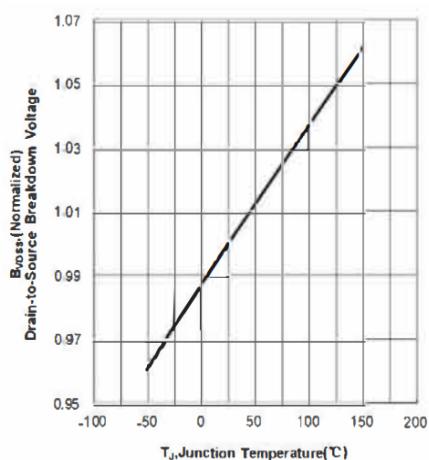
NOTE:

①Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

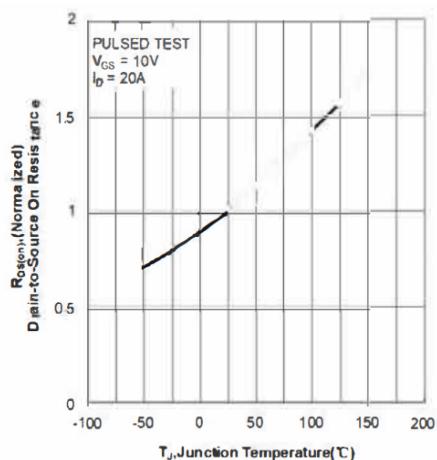
②Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

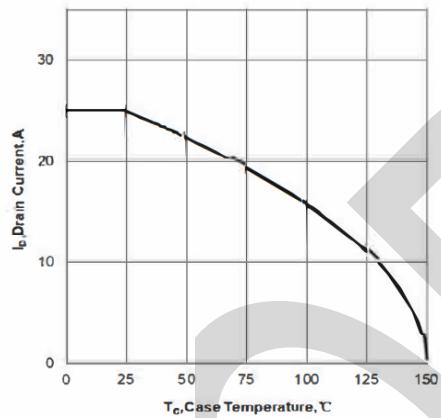




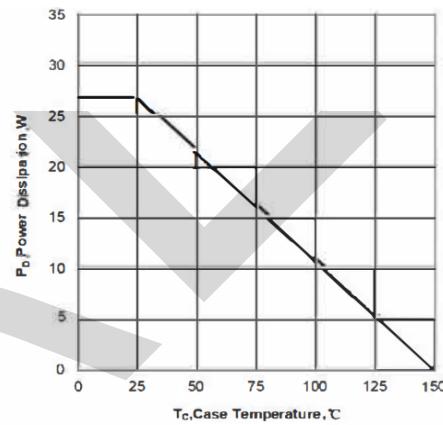
**Figure 7. Normalized Breakdown Voltage
vs Junction Temperature**



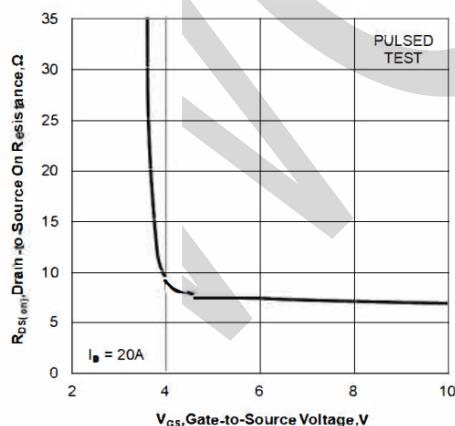
**Figure 8. Normalized On Resistance vs
Junction Temperature**



**Figure 9. Maximum Continuous Drain Current
vs Case Temperature**



**Figure 10. Maximum Power Dissipation
vs Case Temperature**



**Figure 11. Drain-to-Source On Resistance vs Gate
Voltage and Drain Current**

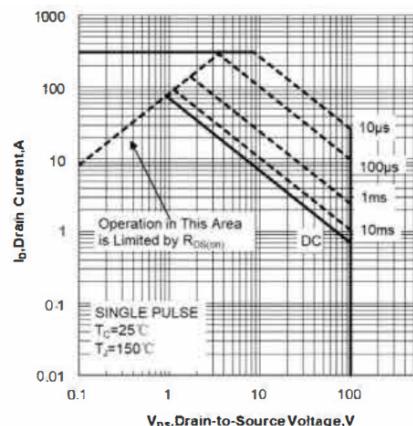


Figure 12. Maximum Safe Operating Area

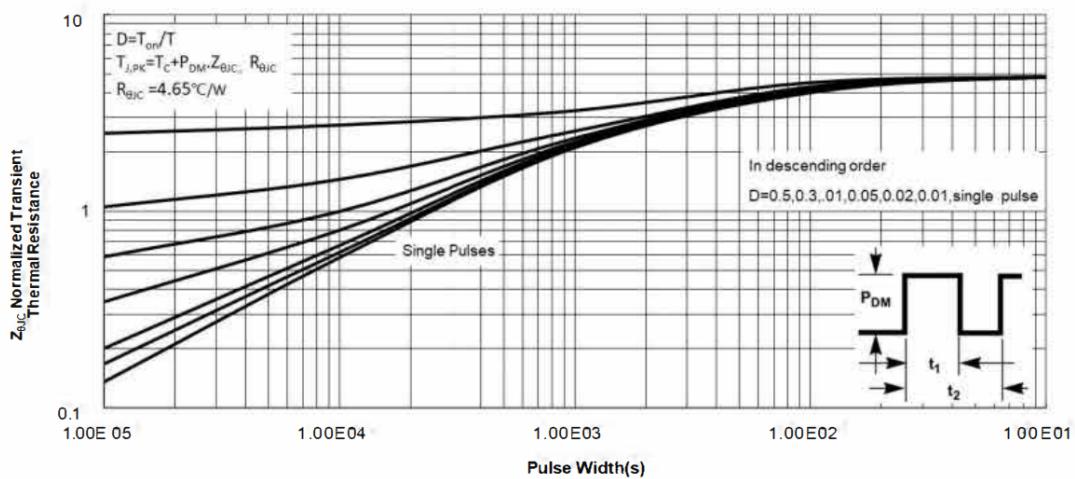
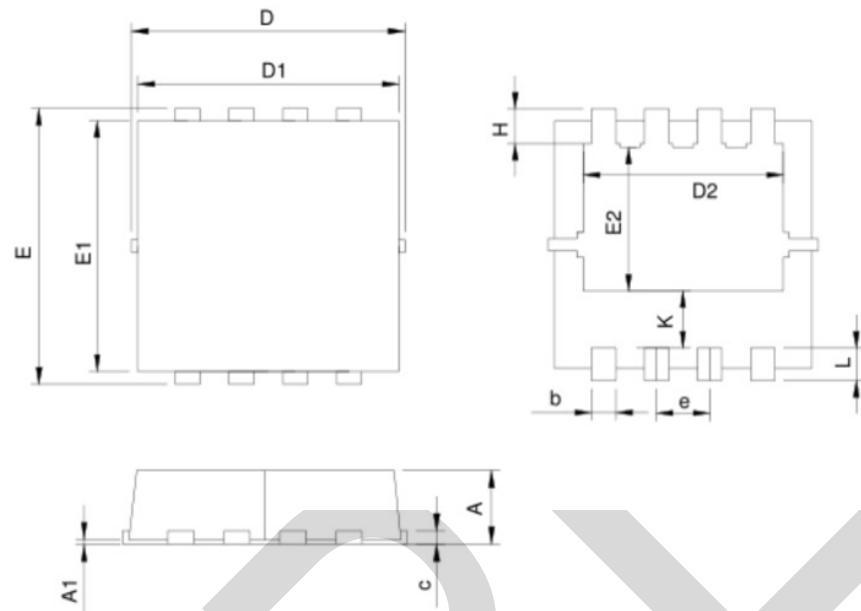


Figure 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

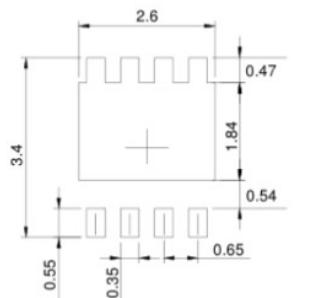
FORV

PACKAGE OUTLINE DIMENSIONS



| SYMBOL | DFN3.3x3.3-8 | | | |
|--------|--------------|------|-----------|-------|
| | MILLIMETERS | | INCHES | |
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.70 | 1.00 | 0.028 | 0.039 |
| A1 | 0.00 | 0.05 | 0.000 | 0.002 |
| b | 0.25 | 0.35 | 0.010 | 0.014 |
| c | 0.14 | 0.20 | 0.006 | 0.008 |
| D | 3.10 | 3.50 | 0.122 | 0.138 |
| D1 | 3.05 | 3.25 | 0.120 | 0.128 |
| D2 | 2.35 | 2.55 | 0.093 | 0.100 |
| E | 3.10 | 3.50 | 0.122 | 0.138 |
| E1 | 2.90 | 3.10 | 0.114 | 0.122 |
| E2 | 1.64 | 1.84 | 0.065 | 0.072 |
| e | 0.65 BSC | | 0.026 BSC | |
| H | 0.32 | 0.52 | 0.013 | 0.020 |
| K | 0.59 | 0.79 | 0.023 | 0.031 |
| L | 0.25 | 0.55 | 0.010 | 0.022 |

RECOMMENDED LAND PATTERN



UNIT: mm